		DEV-ADC34J22 EVM from Dallas Logic					
em #	Quantity	Designator	Comment	Footprint	Manuf1	Manuf1 Partnumber	Description
	0	C1, C5, C6, C7, C8, C9, C10, C11, C12, C15, C16, C17, C18, C19, C20, C21, C22, C23, C24, C25, C28, C29, C30, C32, C34, C35, C36, C40, C41, C42, C47, C49, C50, C52, C53, C54, C55, C56, C61, C64, C65, C66, C67, C69, C69, C70, C31, C37, C31, C31, C49, C31, C49, C61, C69, C61, C69, C61, C69, C61, C69, C61, C69, C61, C69, C61, C61, C61, C61, C61, C61, C61, C61					
		C68, C69, C70, C71, C72, C73, C74, C77, C78, C79, C80, C81, C82, C83, C84, C85, C90, C92, C93, C96, C97, C101	0.1UF	CAPC1005L	Taiyo Yuden	TMK105BJ104KV-F	Capacitor, 0.1UF, 0402, 25V, +-10%, Multi-layer Ceramic X5R, General Purpose
	2 (C2, C3	0.47UF	CAPC1608L	Taiyo Yuden	TMK107BJ474KA-T	Capacitor, 0.47UF, 0603, 25V, +-10%, Multi-layer Ceramic X5R, General Purpose
	3 (C4, C94, C98	10UF	CAPC2012L	Taiyo Yuden	EMK212BJ106KG-T	Capacitor, 10UF, 0805, 16V, +-10%, Multi-layer Ceramic X5R, General Purpose
	2 (C13, C27	1.2PF	CAPC1608L	Vishay	VJ0603A1R2BXACW1BC	Capacitor, 1.2 pf, 0603, 50V, +/1pf, Multiplayer Ceraminc, General Purpose
	6	C31, C33, C39, C45, C48, C103	0.01UF	CAPC1608L	Yageo	CC0603KRX7R9BB103	Capacitor, 0.01UF, 0603, 50V, +-10%, Multi-layer Ceramic X7R, General Purpose
	2 (C37, C43	33PF	CAPC1608L	Kemet	C0603C330G5GACTU	Capacitor, 33PF, 0603, 50V, +-2%, Multi-layer Ceramic C0G, General Purpose
	2 (C38, C44	180PF	CAPC2012L	Kemet	C0805C181G5GACTU	Capacitor, 180PF, 0805, 50V, +-2%, Multi-layer Ceramic C0G, General Purpose
	1 (246	4.7UF	CAPC2012L	Samsung	CL21A475KOFNNNE	Capacitor, 4.7UF, 0805, 16V, +-10%, Multi-layer Ceramic X5R, General Purpose
	1 (251	12PF	CAPC1608L	Kemet	C0603C120J5GACTU	Capacitor, 12PF, 0603, 50V, +-5%, Multi-layer Ceramic NP0, General Purpose
	1 (257	3900PF	CAPC1608L	Kemet	C0603C392J5GACTU	Capacitor, 3900PF, 0603, 50V, +-5%, Multi-layer Ceramic C0G, General Purpose
		C58	56PF	CAPC1608L	Kemet	C0603C560G5GACTU	Capacitor, 56PF, 0603, 50V, +-2%, Multi-layer Ceramic C0G, General Purpose
	2 (C59, C102	100PF	CAPC1608L	TDK Corporation	C1608C0G1H101J	Capacitor, 100PF, 0603, 50V, +-5%, Multi-layer Ceramic C0G, General Purpose
		C60, C100	10PF	CAPC1608L	Panasonic-ECG	ECJ-1VC1H100D	Capacitor, 10PF, 0603, 50V, +-5%, Multi-layer Ceramic C0G, General Purpose
		C14, C26	DNP	CAPC1608L	DNP	DNP	DNP
	-	C62, C63, C86, C87, C88, C89, C91, C95, C191, C192	1UF	CAPC1608L	Taiyo Yuden	TMK107B7105KA-T	Capacitor, 1UF, 0603, 25V, +-10%, Multi-layer Ceramic X7R, General Purpose
		C99	22UF	PCAP3216	NIC Components	NTC-T226K10TRAF	Cap Tant Solid 22uf, 10V, A Case, 10% (3.2mmx1.6mmx1.6mm), SMD 3216-18, 2.5 ohm
		D1, D2, D3	GRN	LED1608L	Liteon Inc	LTST-C190KGKT	LED, 0603, Green, 2.0V, 20mA max, 571nm, clear lens, 130deg, flat
	1.7	=1	2.0A	FUSE0603	Raychem	0603SFV200F/32-2	Fuse, Raychem, 0603, 2.0A, 32V AC, 32V DC, fast acting
		J1, J2, J3, J4, J5, J6	731000114	CON_SMA_RA_THRU	Amphenol RF	731000114	Connector, SMA Jack, Right Anlge, 50 OHM, Thru-hole, Gold, PCB mount, 18 GHz.
		1,L2,L3,L4	1.2NH	IND1608N	Panasonic	ELJ-RE1N2ZFA	Inductor, Panasonic, 0603, 1.2nh, +/- 0.2nh
		.5, L6, L7, L8	250NH	IND1608N	Coilcraft	0603CS-R25XGLW	Inductor, Coilcraft, 0603, 120mA max., 250nH, SRF 0.88 GHz, 3.55 Ohm Max.
		.9, L10, L11, L12, L17, L19, L20, L21, L22, L23, L24, L25	120	IND1608N	Murata	BLM18AG121SN1D	Ferrite bead, Murata, 500mA, 120 Ohm/100 MHz, 0603, 0.18 Ohm DCR.
		.13	1000	INDC4516AN	Murata	BLM41PG102SN1L	Ferrite bead, Murata, 1.5A, 1000 Ohm/100 MHz, 1806, 0.09 Ohm DCR.
		-16 	BLM21AG102SN1D	INDC2012N	Murata	BLM21AG102SN1D	Ferrite bead, Murata, 500mA, 1000 Ohm/100 MHz, 0805, 0.28 Ohm DCR.
			ASP-122952-01	ASP-122952-01	Samtec	ASP-122952-01	Connector, Samtec, HSMC Mezzanine, 5mm stacking height, 0.5mm pitch, Lead Free
		R1, R38, R83, R84, R85 R2, R5, R6, R10, R13, R14, R15, R20, R21, R23, R24, R25, R34, R35, R48,	10.0K	RESC1608L	Yageo Corp	RC0603FR-0710KL	Resistor, 10.0K OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
	16 F		59	RESC1608L	Yageo Corp	RC0603FR-0759RL	Resistor, 59 OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
	4 F	R7, R9, R16, R17 (SHORT)	59	RESC1608L	Yageo Corp	RC0603FR-0759RL	Resistor, 59 OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
	1 F	73	13.3K	RESC1608L	Panasonic Corp.	ERJ-3EKF1332V	Resistor, 13.3K OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		R4, R8, R11, R18, R19, R22, R64	10	RESC1608L	Yageo Corp	RC0603JR-0710RL	Resistor, 10 OHM, 0603, 1/10 watt, 5%, Thick Film, General Purpose
		R36, R49,R52	27.4	RESC1608L	Yageo Corp	RC0603FR-0727R4L	Resistor, 27.4 OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		312	1K	RESC1608L	Yageo Corp	RC0603FR-071KL	Resistor, 1K OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		R26, R37, R40, R50	499	RESC1608L	Yageo	RC0603FR-07499RL	Resistor, 499 Ohm, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		R27, R30, R41, R44	35.7	RESC1608L	Yageo	RC0603FR-0735R7L	Resistor, 35.7 Ohm, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		R28, R29, R42, R43	205	RESC1608L	Yageo Corp	RC0603FR-07205RL	Resistor, 205 OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		R31, R45	442	RESC1608L	Yageo	RC0603FR-07442RL	Resistor 442 Ohm, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		R32, R33, R46, R47	6.2	RESC1608L	Yageo Corp	RC0603JR-076R2L	Resistor, 6.2 OHM, 0603, 1/10 watt, 5%, Thick Film, General Purpose
	31	R39, R51, R99	100	RESC1608L	Yageo Corp	RC0603FR-07100RL	Resistor, 100 OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
	14 F	R63, R66, R67, R70, R73, R74, R53, R54, R55, R56, R57, R58, R59, R60	240	RESC1608L	Yageo Corp	RC0603FR-07240RL	Resistor, 240 OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
	4 F	R62, R65, R75, R78	10M	RESC1608L	Yageo	RC0603JR-0710ML	Resistor, 10M OHM, 0603, 1/10 watt, 5%, Thick Film, General Purpose
	-	R68, R72	33	RESC1608L	Yageo Corp	RC0603JR-0733RL	Resistor, 33 OHM, 0603, 1/10 watt, 5%, Thick Film, General Purpose
	1.1	R69	680	RESC1608L	Yageo Corp	RC0603FR-07680RL	Resistor, 680 OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
	3 F	R71, R76, R77	330	RESC1608L	Yageo Corp	RC0603JR-07330RL	Resistor, 330 OHM, 0603, 1/10 watt, 5%, Thick Film, General Purpose
	1 F	R86	47K	RESC1608L	Yageo Corp	RC0603JR-0747KL	Resistor, 47K OHM, 0603, 1/10 watt, 5%, Thick Film, General Purpose
		787	20.0K	RESC1608L	Yageo Corp	RC0603FR-0720KL	Resistor, 20.0K OHM, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		R88	2.0	RESC1608L	Yageo	RC0603FR-072RL	Resistor, 2.0 Ohm, 0603, 1/10 watt, 1%, Thick Film, General Purpose
		R89	430	RESC1608L	Yageo Corp	RC0603JR-07430RL	Resistor, 430 OHM, 0603, 1/10 watt, 5%, Thick Film, General Purpose
		F1, T2	9.0V-0.1J	TVS0603	AVX	VC060309A200DP	Bidirectional Tranzorb, AVX, 0603, 9.0V, 0.1J, 30A peak, 550pF, 22V clamp
		F3	3.3V-0.1J	TVS0603	AVX	VC060303A100DP	Bidirectional Tranzorb, AVX, 0603, 3.3V, 0.1J, 30A peak, 1450pF, 12V clamp
		J1	SN74LVC1G17	SC70-5	Texas Instruments	SN74LVC1G17DCKR	Buffer, Schmitt trigger, +-32mA, LVC compatible, 1.65-5.5V
		J2	TPS7A8101DRBT	SON-3x3mm	Texas Instruments	TPS7A8101DRBT	LDO, Var. 0.8V-6.0V, 1A, 7V Max. input, Low Noise, 3mmx3mm, SON-8
		J3, U4, U5, U6	WBC1-1TLB	WBC1-TLB_minicircuits	Coilcraft	WBC1-1TLB	RF Transformer, Coilcraft, 75 ohm, 0.4-600Mhz, IL 0.4 dB, DCR 0.75 mOhm
	_	J7, U10	BAV99W-7-F	SOT-323_diodes	Diodes Inc	BAV99W-7-F	Dual diode, Switching, Diodes Inc., vf 1.25V at 150mA, vr = 100V.
		J8 (SHORT)	ADC34J22	QFN48_L_ti_adc	TI	ADC34J22	AD Converter, TI, Quad Channel, 12bit, 50 MSPS, JESD204B Interface
	-	J9, U11	THS4541IRUN	WQFN10-2x2mm		THS4541IRUN	Diff. Amplifier TI, Single Channel, 750 MHz, VCC at 2.7V-5.4V or +/-1.35V-2.7V
		J12	CVHD-950-100.000	9X14MMSMD_CRYSTEK	Crystek Crystals	CVHD-950-100.000	Oscillator, VCXO, 100 MHz, HCMOS, 3.3V, 0C - 70C
	111	J13	LMK04828BISQE/NOPB	WQFN-64N_ti_Imk_modified	11	LMK04828BISQE/NOPB	Clock Jitter Cleaner, TI, 3input, 7output, programmable output type, 3.3V
		J14	ASTX-H12-10.000MHZ-T	2.5X2.0MMSMD ABRACON	Abracon Corporation	ASTX-H12-20.000MHZ-T	TXCO, 10 MHz, 3.3V, 2.5 x 2.0 mm SMD, +-2.5ppm, -30 to 75 C, 4.8mA

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